



**THE DATASHEET OF
BD3812F-E2**



Sound Processors for Home Theater Systems

2ch Electronic Volume



BD3812F

No.10081EAT03

●Description

BD3812F is an electronic volume having volume, gain amplifier functions necessary for applications in AV receivers, home theatre systems, min-component systems and so forth. Having a chip select terminal, it can be controlled until 4 chips with common bus line.

●Features

- 1) Residual noise : 1.2 μ Vrms {dynamic range : 131dB (IHF-A)}
- 2) 2ch independent volume (0 to -103dB, MUTE 1dB/step)
- 3) 8ch at maximum available in combination of any of BD3811K1, BD3813KS, BD3814FV, BD3815KS (6ch volume) in common bus line
- 4) It can be controlled until 4 chips with common bus line at the same time
- 5) Maximum output voltage : 4.2Vrms (Vcc=7, VEE=-7V, RL=10k Ω)
- 6) 2-line serial control (for both 3.3V and 5V)
- 7) Built-in Output gain amplifier for adjustment of output signal voltage (0, 6 to 18dB, 2dB/step)
- 8) Output mute controllable by serial data and external control terminal

●Applications

AV receivers, home theater systems, mini-component systems, etc.

●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power supply voltage	VCC	7.5 ^{*1}	V
	VEE	-7.5	
Input signal voltage	VIN	VCC+0.3 to VEE-0.3	V
Power dissipation	Pd	450 ^{*2}	mW
Operating temperature range	Topr	-20 to +75	°C
Storage temperature range	Tastg	-55 to +125	°C

*1 Even in the specified range of Power Supply Voltage, applying voltage only to the VCC side may cause an excessive current to give a permanent damage to the IC.

When starting up power supplies, VEE and VCC should be powered on simultaneously or VEE first; then followed by VCC.

*2 Over Ta=25°C, reduce at the rate of 4.5mW/°C. When installed on the standard board (size: 70x70x1.6mm).

●Operating conditions

It must function normally at Ta=25°C.

Parameter	Symbol	Ratings			Unit
		Min.	Typ.	Max.	
Operating source voltage	VCC	5	7	7.3	V
	VEE	-7.3	-7	-5	

●Electrical characteristics

Ta=25°C, VCC=7V, VEE=-7V, f=1kHz, Vin=1Vrms, RL=10kΩ, Rg=600Ω, Master volume=0dB, Output gain=0dB, unless otherwise specified.

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Circuit current	VCC	—	2	6	mA	No signal
	VEE	-6	-2	—		
Output voltage gain	Gv	-2	0	2	dB	Measure : Pin14, 13
Total harmonic distortion ratio	THD	—	0.005	0.09	%	Measure : Pin14, 13 BW=400~30kHz
Maximum output voltage	Vomax	3.4	4.2	—	Vrms	Measure : Pin14, 13 THD=1%
Output noise voltage	Vno	—	1.2	5	μVrms	Measure : Pin 14, 13 Rg=0Ω, BW=IHF-A
Input impedance	Rin	20	30	40	kΩ	Measure : Pin1, 3
Cross talk between channels 1ch→2ch	CTC12	—	-100	-70	dB	Measure : Pin13(OUT2) Rg=0Ω, BW=IHF-A Reference : Pin14(OUT1)=1Vrms
Cross talk between channels 2ch→1ch	CTC21	—	-100	-70	dB	Measure : Pin14(OUT1) Rg=0Ω, BW=IHF-A Reference : Pin13(OUT2)=1Vrms
Volume control range	GVR	-106	-103	-100	dB	Measure : Pin 14, 13 Vin=3Vrms
Volume set error 1	VE1	-2	0	2	dB	Measure : Pin 14, 13 0 to -53dB, Vin=3Vrms
Volume set error 2	VE2	-3	0	3	dB	Measure : Pin 14, 13 -54 to -103dB, Vin=3Vrms
Maximum attenuation	Vmin	—	-118	-105	dB	Measure : Pin 14, 13 BW=IHF-A, Vin=3Vrms
Output gain control range	GOG	16	18	20	dB	Measure : Pin 14, 13 Vin=0.4Vrms
Output gain set error	GOE	-2	0	-2	dB	Measure : Pin 14, 13 Vin=0.4Vrms

* This product is not of "anti radiation design".

●Timing chart

1) Signal timing conditions

- Data is read on the rising edge of the clock.
 - Latch is read on the falling edge of the clock.
 - Latch signal must terminate with the LOW state.
- * To avoid malfunctions, clock and data signals must terminate with the LOW state.

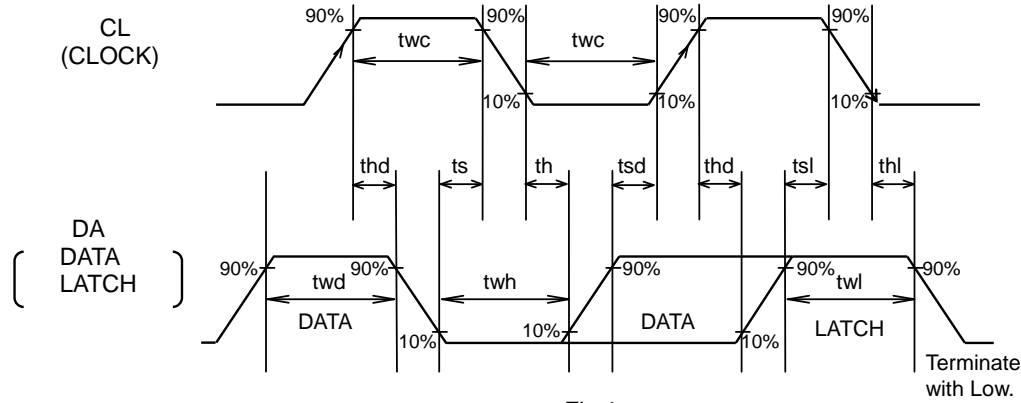


Fig.1

Parameter	Symbol	Limits			Unit
		Min.	Typ.	Max.	
Minimum clock width	twc	2.0	—	—	μs
Minimum data width	twd	2.0	—	—	μs
Minimum latch width	twl	2.0	—	—	μs
LOW hold width	twh	2.0	—	—	μs
Data setup time (DATA→CLK)	tsd	1.0	—	—	μs
Data hold time (CLK→DATA)	thd	1.0	—	—	μs
Latch setup time (CLK→LATCH)	tsl	1.0	—	—	μs
Latch hold time (DATA→LATCH)	thl	1.0	—	—	μs
Latch low setup time	ts	1.0	—	—	μs
Latch low hold time	th	1.0	—	—	μs

2) Voltage conditions for control signal

Parameter	Condition	Limits			Unit
		Min.	Typ.	Max.(≤Vcc)	
“H”input voltage	Vcc=5~7.3V	2.2	—	5.5	V
“L” input voltage	VEE=-5~-7.3V	0	—	1.0	V

3) Basic configuration of control data format

← Input direction

	MSB															LSB	
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	Data														Select Address		

• Control data format

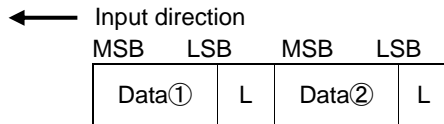
← Input direction

															Select Address		
Data ①	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	Master Volume 2ch							Master Volume 1ch							1	1	0
Data ②	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	*	*	*	*	*	*	*	*	*	*	*	Output gain amp			1	1	1

* is 0 or 1.

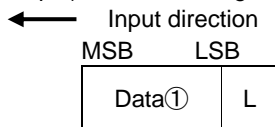
By changing the setting of select address, 4 control data formats can be selected.
Do not set the select address data to other than specified above.

At power on, initialize all the data.



"L" shows latch.

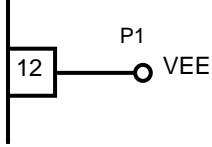
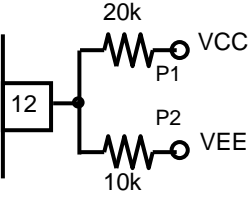
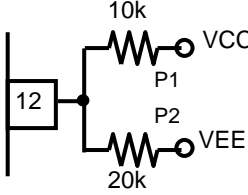
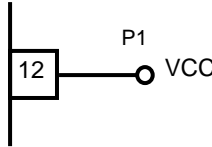
After power on, in the second time or after, only data you want to change can be set.
(Example) When to change bus



"L" shows latch.

4) SEL terminal setting

By determining the SEL terminal voltage, select address can be fixed.
An example of the SEL terminal voltage setting method is shown below.

Setting	P1 Condition	P2 Condition	Setting of SEL(12pin) Terminal	SEL(12pin) Terminal Voltage(V)	Select Address	
					D2	D1
Setting 1	VEE	—		VEE	0	0
Setting 2	VCC	VEE		$VCC/3+2 \times VEE/3$	0	1
Setting 3	VCC	VEE		$VCC/3$	1	0
Setting 4	VCC	—		VCC	1	1

SEL terminal voltage is DGND standard.

When to use several chips of BD3812F

Select address can be changed by setting SEL terminal (12pin), therefore, up to 4 chips can be used on a same bus line. When to use one chip or two chips of this IC, use the setting 1 and the setting 4. In this case, the terminal voltage of 12pin may be VCC or VEE, therefore external resistor of 12pin is unnecessary.

When to use BD3812F and BD3811K1 at the same time

By using BD3812F and BD3811K1 at the same time, independent control of 8ch volume can be made. And control is available on a same bus line. In this case, be sure to set the SEL terminal setting to “setting 4”.

●Application circuit

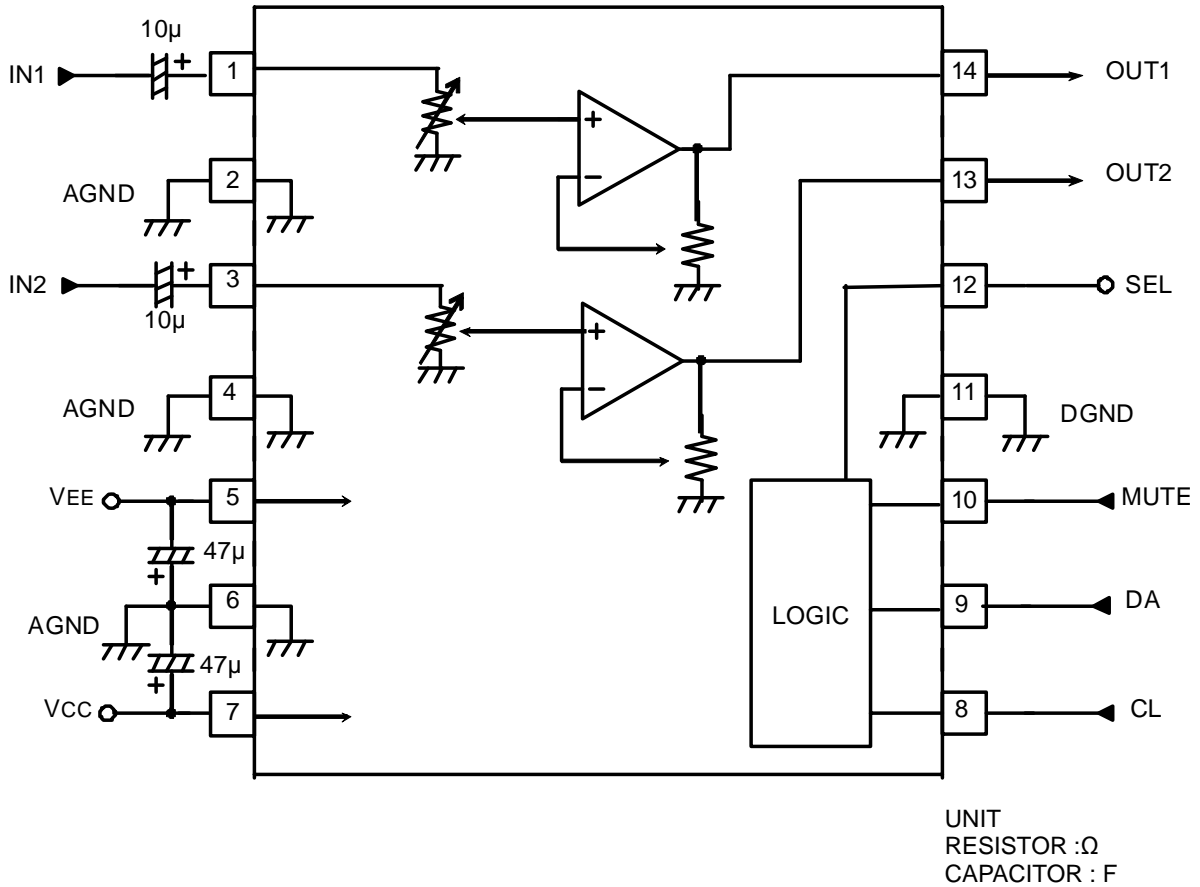


Fig.2

●Reference data

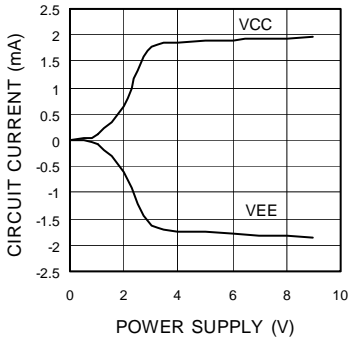


Fig.3 Circuit current - Power supply

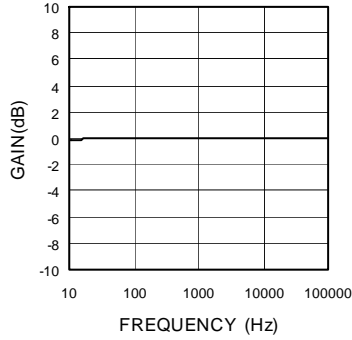


Fig.4 Voltage gain - Frequency

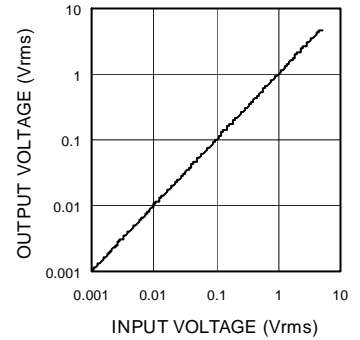


Fig.5 Output voltage - Input voltage

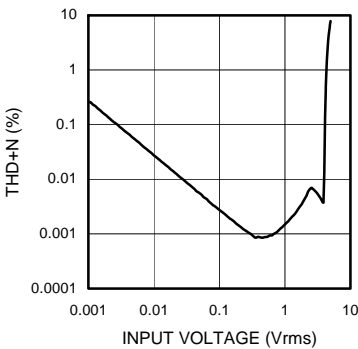


Fig.6 THD+N - Input voltage

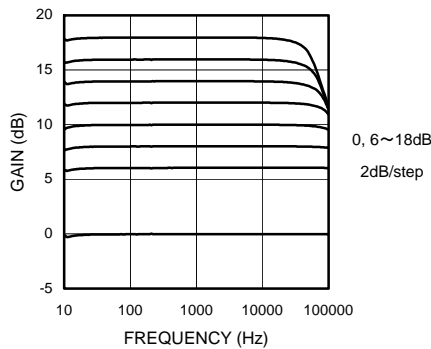


Fig.7 Output gain - Frequency

●Notes for use

- (1) Numbers and data in entries are representative design values and are not guaranteed values of the items.
- (2) Although we are confident in recommending the sample application circuits, carefully check their characteristics further when using them. When modifying externally attached component constants before use, determine them so that they have sufficient margins by taking into account variations in externally attached components and the Rohm LSI, not only for static characteristics but also including transient characteristics.
- (3) Absolute maximum ratings
If applied voltage, operating temperature range, or other absolute maximum ratings are exceeded, the LSI may be damaged. Do not apply voltages or temperatures that exceed the absolute maximum ratings. If you think of a case in which absolute maximum ratings are exceeded, enforce fuses or other physical safety measures and investigate how not to apply the conditions under which absolute maximum ratings are exceeded to the LSI.
- (4) VEE potential
Make the VEE pin voltage such that it is the lowest voltage even when operating below it. Actually confirm that the voltage of each pin does not become a lower voltage than the VEE pin, including transient phenomena.
- (5) Thermal design
Perform thermal design in which there are adequate margins by taking into account the allowable power dissipation in actual states of use.
- (6) Shorts between pins and misinstallation
When mounting the LSI on a board, pay adequate attention to orientation and placement discrepancies of the LSI. If it is misinstalled and the power is turned on, the LSI may be damaged. It also may be damaged if it is shorted by a foreign substance coming between pins of the LSI or between a pin and a power supply or a pin and a GND.
- (7) Operation in strong magnetic fields
Adequately evaluate use in a strong magnetic field, since there is a possibility of malfunction.
- (8) Serial control
For the CL and DA terminals, the patterned and other wirings should be routed not to cause interference with the analog-signal-related lines.
- (9) About power ON/OFF
 - (a) At power ON/OFF, a shock sound will be generated and, therefore, use MUTE on the set.
 - (b) When turning on power supplies, VEE and VCC should be powered on simultaneously or VEE first; then followed by VCC. If the VCC side is started up first, an excessive current may pass VCC through VEE.
- (10) Function switching
For the functions except master volume, use MUTE on the set.
- (11) Reduction of switching noise when changing volume from -3dB to -4dB
In order to reduce switching noise when changing volume from -3dB to -4dB, after switching the switch of -4dB step, change the switch of -1dB step by -1dB.

●Thermal derating characteristic

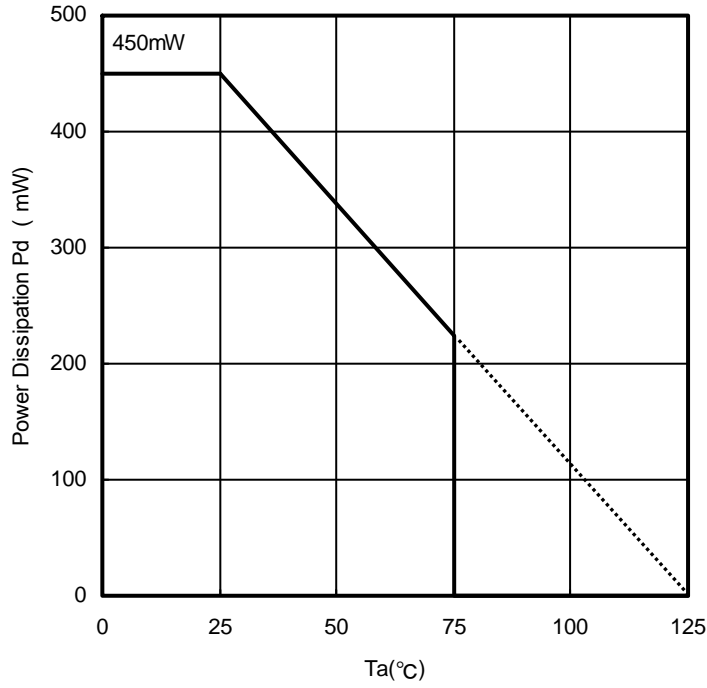


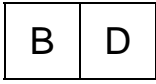
Fig.8

BD3812

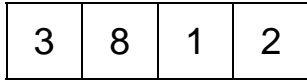
ROHM standard board packaging time value

Board size : 70 x 70 x 1.6mm Raw material : FR4 glass epoxy board (copper area 3% or below)

●Ordering part number



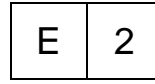
Part No.



Part No.

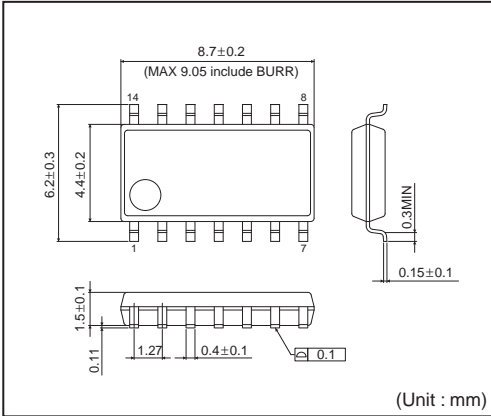


Package
F:SOP14



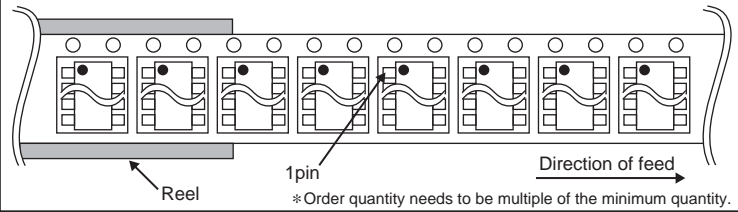
Packaging and forming specification
E2: Embossed tape and reel

SOP14



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



Notice

Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - Installation of protection circuits or other protective devices to improve system safety
 - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
 - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

Precaution Regarding Intellectual Property Rights

1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data. ROHM shall not be in any way responsible or liable for infringement of any intellectual property rights or other damages arising from use of such information or data.:
2. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the information contained in this document.

Other Precaution



1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

General Precaution

1. Before you use our Products, you are requested to carefully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any ROHM's Products against warning, caution or note contained in this document.
2. All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sales representative.
3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate and/or error-free. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View BD3812F-E2](#) on WIN SOURCE
-  [Rohm Semiconductor](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management